



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSP742T	Issued	05. February 2022
MA#	MA001427676		
Package	PG-DSO-8-24	Weight*	83.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.250	1.50	1.50	15045	15045
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.717	0.86		8634	
	non noble metal	copper	7440-50-8	29.121	35.06	35.97	350564	359738
wire	noble metal	gold	7440-57-5	0.373	0.45	0.45	4491	4491
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1193	
	plastics	epoxy resin	-	4.560	5.49		54898	
	inorganic material	silicondioxide	60676-86-0	44.910	54.07	59.68	540628	596719
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9797	9797
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7828	7828
glue	plastics	epoxy resin	-	0.093	0.11		1117	
	noble metal	silver	7440-22-4	0.437	0.53	0.64	5265	6382
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com